

ASEK720, Board, Demo, S0IC16

85-0804-002-FAB
Originator: S. Upton

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	TopPaste				
2	TopOverlay				
3	TopSolder	Solder Resist	0.40mil	3.5	
4	TopLayer	Copper	2.80mil		
5	Dielectric	FR-4	17.87mil	4	
6	Signal Layer 1	Copper	1.42mil		
7	Dielectric 3		17.87mil	4.2	
8	Signal Layer 2	Copper	1.42mil		
9	Dielectric 2		17.87mil	4.2	
10	BottomLayer	Copper	2.80mil		
11	BottomSolder	Solder Resist	0.40mil	3.5	
12	BottomOverlay				
13	BottomPaste				

Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
x	2	56.00mil (1.422mm)	PTH	Round
o	2	61.02mil (1.550mm)	PTH	Round
■	2	266.00mil (6.756mm)	PTH	Round
◊	4	125.00mil (3.175mm)	PTH	Round
o	6	28.00mil (0.711mm)	PTH	Round
o	6	42.00mil (1.067mm)	PTH	Round
v	10	31.50mil (0.800mm)	PTH	Round
■	12	62.00mil (1.575mm)	PTH	Round
□	102	15.00mil (0.381mm)	PTH	Round
	146 Total			

Mechanical Layer 1 *.gml is Board Outline, slots and circular cutouts
 Mechanical Layer 2 *.gms2 is footprint notes (not for fab house)
 Mechanical Layer 3 *.gms3 is hole location guide
 Mechanical Layer 4 *.gml is board outline dimensions
 Mechanical Layer 5 *.gms5 is topside labels (if no silk)
 Mechanical Layer 6 *.gms6 is bottomside labels (if no silk)
 Mechanical Layer 7 *.gms7 is FAB drawing notes
 Mechanical Layer 8 *.gms8 is top selective hard gold
 Mechanical Layer 9 *.gms9 is bottom selective hard gold
 Mechanical Layer 10 and up are not for usage by PCB board house
 *.gto and *.gbo are top and bottom layer silkscreen (aka overlay)
 *.gts and *.gbs are top and bottom soldermask
 *.drl is NC Drill
 *.apr is aperture file
 *.gpb and *.gpt are pad master layers, and are not used (ignore if in zip file)
 Keepout layer *.gko is for internal usage only, and is not to be used by board house

FAB Drawing / FAB Notes and Requirements

Rev 1
7/28/2015

- Finished PCB is RoHS
- Dimensions are in inches, unless otherwise noted.
- Applicable Standards:
 - Manufacture in accordance to IPC-6011, IPC-6012 for Class 2 applications.
 - PCB shall meet acceptance criteria as required for Class 2 PCB as defined in IPC-600
 - UL Approved to a minimum category of 94U0.
- Laminate:
 - Thickness: 0.062inch +/- 10%
 - Type: high temp FR4
 - this line left blank
 - Core/prepreg thickness:
 - See chart to left.
 - Core/prepreg thicknesses to be roughly uniform thickness or +/-5mil from indicated
 - No impedance controlled stackup required
- Copper:
 - Layer Count: 4
 - Exterior layers: 2oz min
 - Interior layers: 1oz min
 - Plated through holes: plate to 1mil min copper thickness
 - Trace separation: 10mil
 - Trace min width: 10mil
 - Line width reduction due to pinholes nicks or shrinking: 20% max.
 - No impedance controlled route used; no trace width adjustment required.
- this line left blank
- Total board flatness shall not exceed 0.002inch per inch.
- Artwork layer registration shall be within 0.003inch total.
- Surface Finish:
 - Immersion Gold
 - No hard gold required, no *.gm8 nor *.gm9 layer provided
- Soldermask:
 - Top/Bottom soldermask required
 - Soldermask color shall be green.
 - Soldermask finish may be matte or glossy.
- Silkscreen
 - Top/bottom silkscreen required.
 - Silkscreen color shall be white.
 - Min silkscreen line width: 8mil
 - Epoxy or acrylic ink allowed
- Drill holes:
 - No blind or buried vias.
 - Hole sizes are specified after plating.
 - No via in pad used. No via filling required.
- Mill separate or U-score according to mech1 (*.gml) layer.
- Electrical testing required.
- Contact information:
 - Shaun Upton supton@allegromicro.com, 603.626.2429
 - If fast turn board, 24hr contact info: N/A





